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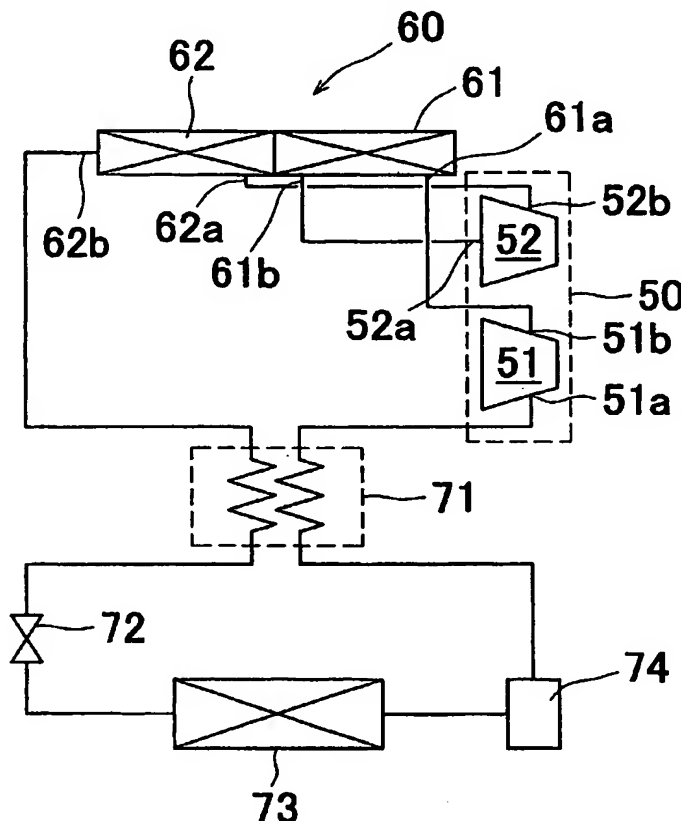
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(54) Title: REFRIGERATION SYSTEM, COMPRESSING AND HEAT-RELEASING APPARATUS AND HEAT-RELEASING
DEVICE



(57) Abstract: A refrigeration system according to the present invention is provided with a two-stage type compressor 50 having independent low-pressure and high-pressure compressing portions 51 and 52, a heat-releasing device 60 having independent primary and secondary heat-releasing paths 61 and 62, an expansion valve 72 and a cooler 73. The refrigerant primarily compressed by the low-pressure compressing portion 51 is primarily released in heat by the primary heat-releasing path 61. The primarily heat-released refrigerant is secondarily compressed by the high-pressure compressing portion 52. The secondarily compressed refrigerant is secondarily released in heat by the secondary heat-releasing path 62 to thereby obtain a low-temperature and high-pressure refrigerant. The low-temperature and high-pressure refrigerant is decompressed and expanded by the expansion valve 72 and passes through the cooler 73 to absorb the heat in a room air, and then returns to the low-pressure compressing portion 51 of the compressor 50. In this system, the refrigerant temperature during the heat-releasing procedure can be kept low.